



Sn62Pb36Ag2 - Low temperature (LMP) solder alloy for soldering equipment in electronics, telecommunications, rework or SMT. Being nearly Eutectic this alloy offers good flow characteristics and the alloy combination gives bright, high integrity joints.

Conform to standards: NF 90550 –DIN 1707-8511 –QQS 571E –MIL.F.142560

B.S.219 code 62S, BS EN alloy No.30.

ADDITIONAL INFORMATION:

Our manufacturing processes have been subjected to FMECA analysis (equivalent of AMDEC in Europe).

Chemical Characteristics

Amount of Tin:	62 % ± 0.7%
Amount of Copper:	36% ± 0.4%
Amount of Silver:	2%. ± 0.1%
Tin-lead-silver double refined at first melting, electrolytic silver purity of 99.99 %	

Chart of maximum impurities, example:

Cu	Cd	Sb
0.05%	0.002%	0.05%

Bi	Fe	Zn
0.01%	0.02%	0.001%

Al	As	Others
0.001%	0.01%	0.05%

Physical Characteristics, standard:

Melting point	Solidus @ 178°C to Liquidus @ 180°C
Specific weight	8.4 g/cm
Working temperature	220 - 240 °C (typical)

Packaging

- Bars: Extruded approx. 900g bars in cartons of 24 off.
(Exact Tare weight stated)
- Sticks: 320g in cartons of 25 Kgs.
- Granules: In 10 - 25 Kg Bucket
- Ingots: Approximately 3.9 Kgs.
- Wire: On spools of 15 Kgs - 20 Kgs.

Storage

In Original packaging, at room temperature for 12 months